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July 2011

FDS86106

N-Channel Power Trench[®] MOSFET 100 V, 3.4 A, 105 m Ω

Features

- Max $r_{DS(on)} = 105 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 3.4 \text{ A}$
- Max $r_{DS(on)}$ = 171 m Ω at V_{GS} = 6 V, I_D = 2.7 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- 100% UIL Tested
- RoHS Compliant

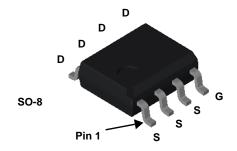


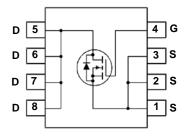
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- Synchronous Rectifier
- Primary Switch For Bridge Topology





MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous			3.4	^
ID	-Pulsed			15	- A
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	13	mJ
D	Power Dissipation	T _A = 25 °C	(Note 1a)	5.0	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1b)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Temperature R	Range		-55 to +150	°C

Thermal Characteristics

R_{ϵ}	θЈС	Thermal Resistance, Junction to Case	(Note 1)	2.5	°C/W
R_{ϵ}	θЈΑ	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS86106	FDS86106	SO-8	13 "	12 mm	2500 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		67		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	2.9	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-9		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 3.4 \text{ A}$		83	105	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 2.7 \text{ A}$		115	171	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 3.4 \text{ A}, T_J = 125 \text{ °C}$		143	177	
g _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 3.4 \text{ A}$		6		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 50 V V 0 V	156	208	pF
C _{oss}	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	47	62	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	2	3	pF
R _a	Gate Resistance		0.9		Ω

Switching Characteristics

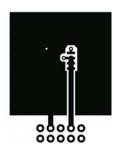
t _{d(on)}	Turn-On Delay Time		5	10	ns
t _r	Rise Time	$V_{DD} = 50 \text{ V}, I_D = 3.4 \text{ A},$	2	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	8	15	ns
t _f	Fall Time		2	10	ns
0	Total Gate Charge	V _{GS} = 0 V to 10 V	3	4	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $V_{DD} = 50 \text{ V}$	1.6	2.3	nC
Q_{gs}	Total Gate Charge	I _D = 3.4 A	0.8		nC
Q_{gd}	Gate to Drain "Miller" Charge		0.8		nC

Drain-Source Diode Characteristics

V	I Source to Drain Dioge Forward voltage	$V_{GS} = 0 \text{ V}, I_{S} = 3.4 \text{ A}$	(Note 2)	0.86	1.3	V
v SD		$V_{GS} = 0 \text{ V}, I_{S} = 2.1 \text{ A}$	(Note 2)	0.83	1.2	, v
t _{rr}	Reverse Recovery Time	L = 3.4 A di/dt = 100 A/		34	54	ns
Q _{rr}	Reverse Recovery Charge	I _F = 3.4 A, di/dt = 100 A/μs		22	35	nC

NOTES

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,1C} is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

^{2.} Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0 %.

^{3.} Starting T_J = 25 $^oC;$ N-ch: L = 3 mH, I_{AS} = 3 A, V_{DD} = 100 V, V_{GS} = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

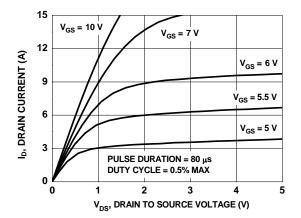


Figure 1. On-Region Characteristics

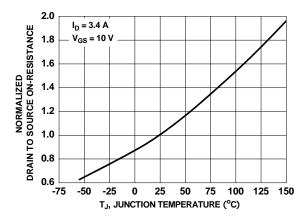


Figure 3. Normalized On-Resistance vs Junction Temperature

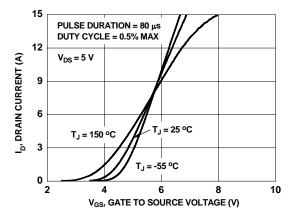


Figure 5. Transfer Characteristics

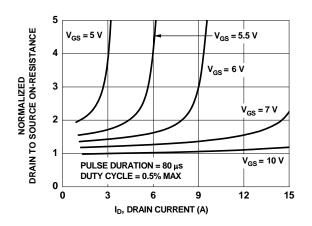


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

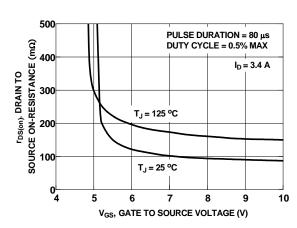


Figure 4. On-Resistance vs Gate to Source Voltage

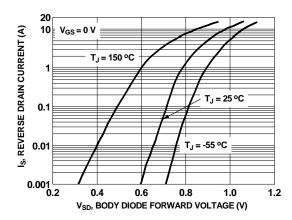


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

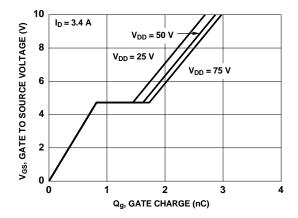


Figure 7. Gate Charge Characteristics

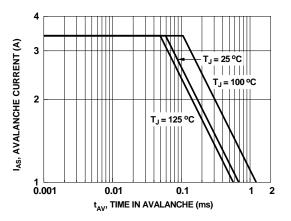


Figure 9. Unclamped Inductive Switching Capability

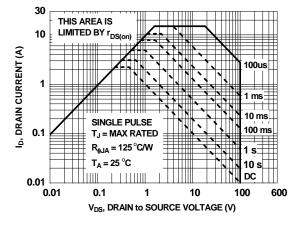


Figure 11. Forward Bias Safe Operating Area

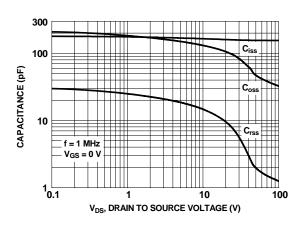


Figure 8. Capacitance vs Drain to Source Voltage

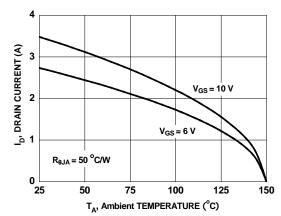


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

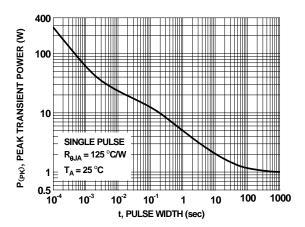


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

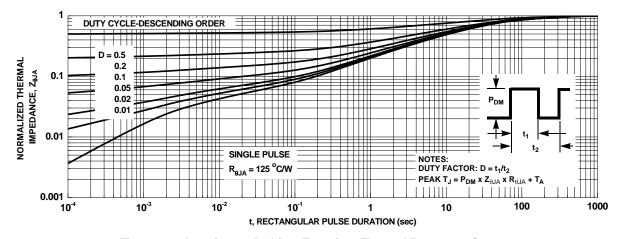


Figure 13. Junction-to-Ambient Transient Thermal Response Curve





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